



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Min-Lung HUANG et al. Confirmation No: 8687  
Appl. No. : 10/820,855  
Filed : April 9, 2004  
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2814  
Examiner : A. Kalam

Docket No.: : HUAN3262/REF  
Customer No: : 23364

**PETITION FOR EXTENSION OF TIME**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Applicants request that the period for response to the outstanding official action in this case be extended pursuant to 37 CFR 1.136 (a) for THREE (3) months to February 27, 2008.

The fee set in 37 CFR 1.17(a)(2) for a three month extension of time is \$1,050.00, however a check in the amount of \$120.00 for a one (1) month extension of time was submitted on December 27, 2007. Therefore, a check in the amount of \$930.00 of the balance due is submitted herewith. Please charge any additional fee required for this extension to Deposit Account No. 02-0200. A duplicate copy of this paper is attached.

Respectfully submitted,  
BACON & THOMAS, PLLC

By: Richard E. Fichter  
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February 26, 2008

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